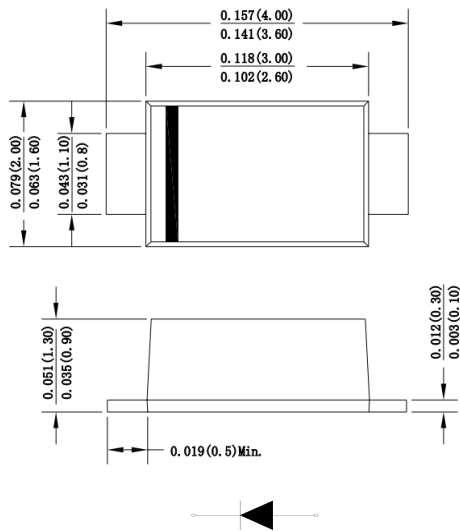


2Amp Standard Surface Mounted Rectifiers

**SOD-123FL**



Dimensions in inches and (millimeters)

**Features**

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
250°C/10 seconds at terminals

**Mechanical Data**

**Case** : Molded plastic body

**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity** : Polarity symbol marking on body

**Mounting Position** : Any

**Weight** : 0.0007 ounce, 0.02 grams

**Maximum Ratings And Electrical Characteristics**

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	S2AW	S2BW	S2DW	S2GW	S2JW	S2KW	S2MW	UNITS
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T <sub>L</sub> =100°C	I <sub>(AV)</sub>	2							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	40.0							A
Maximum instantaneous forward voltage at 1.5A	V <sub>F</sub>	1.10							V
Maximum DC reverse current T <sub>A</sub> =25°C at rated DC blocking voltage T <sub>A</sub> =125°C	I <sub>R</sub>	5.0 500							uA
Typical junction capacitance (Note1)	C <sub>J</sub>	21.0							pF
Typical thermal resistance	R <sub>qJA</sub>	85.0							°C/W
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150							°C

**Ratings And Characteristic Curves**

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

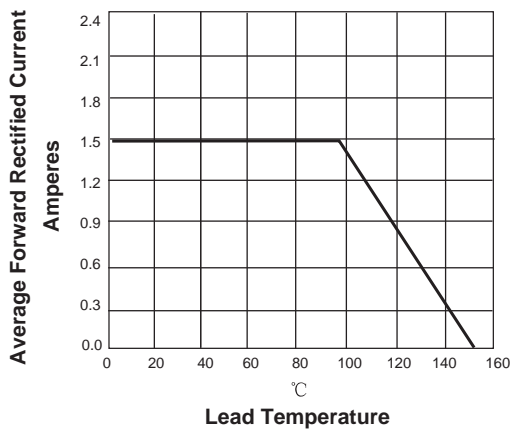


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

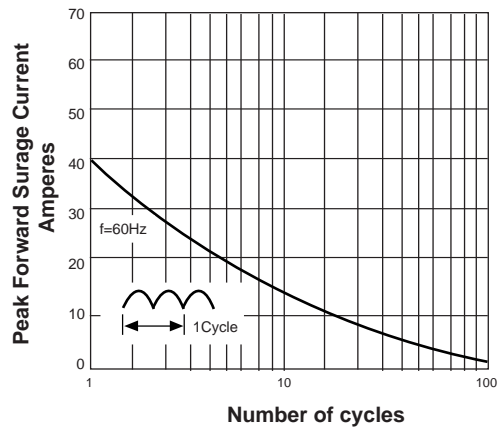


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

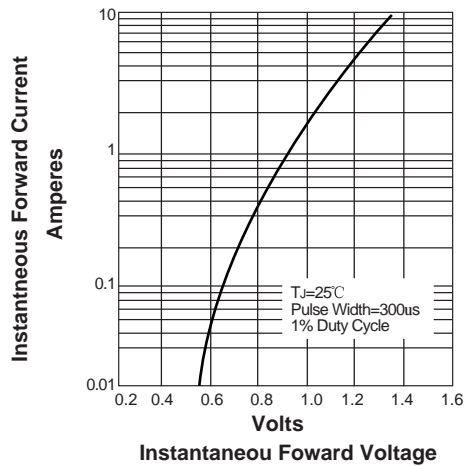
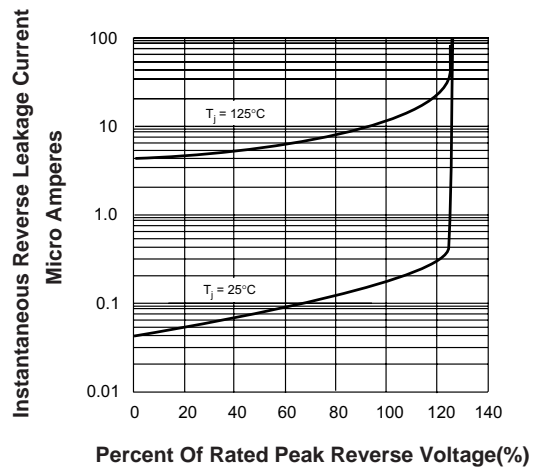
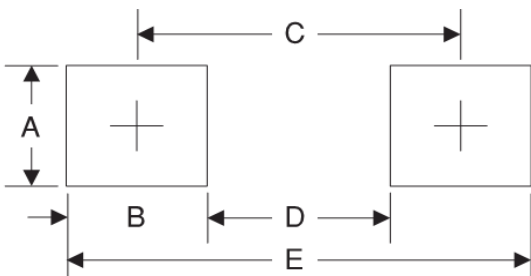


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

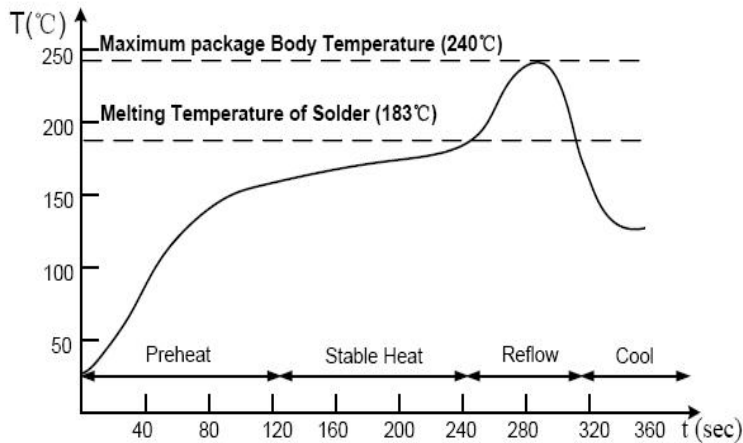


**Suggested Pad Layout**



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.048
B	1.15	0.045
C	3.10	0.122
D	1.95	0.077
E	4.25	0.167

## Suggested Soldering Temperature Profile

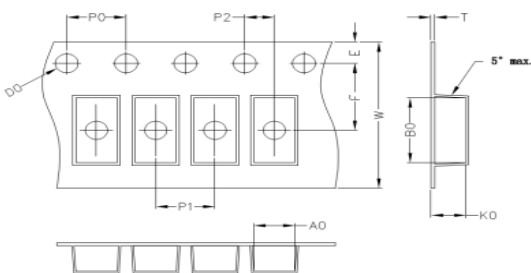


### Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

### Carrier Dimension(mm)



<b>A0</b>	<b>B0</b>	<b>K0</b>	<b>D0</b>	<b>E</b>	<b>F</b>
2.15	3.95	1.35	1.55	1.75	3.50
<b>P0</b>	<b>P1</b>	<b>P2</b>	<b>T</b>	<b>W</b>	<b>Tolerance</b>
4.0	4.0	2.0	0.25	8	0.1

### Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SOD123FL	7'	178	3	180	15	380*200*200	150

单击下面可查看定价，库存，交付和生命周期等信息

[>>DIOS\(迪恩思\)](#)